

Project Number: Design Qua	Trackin	g Code: 218303	_Report_I	Rev 2			
Requested by: Eric Mings		Date: 11/16/2012 Product Re		Rev: AM			
Part #: HSEC8-150-01-S-DV-A/Daughter Card			Lot #: N/A Tech: Aaron M		cKim	Eng: Eric Mings	
Part description: High Speed Edge Card Assembly		ý				Qty to	test: 112
Test Start: 10/11/2012	Test Completed: 11/	/12/2012					



Design Qualification Report

HSEC8

HSEC8-150-01-S-DV-A HSEC8-1100-01-S-DV-A HSEC8-110-01-S-DV-A

 Tracking Code: 218303_Report_Rev 2
 Part #: HSEC8-150-01-S-DV-A/Daughter Card

 Part description: High Speed Edge Card Assembly

REVISION HISTORY

DATA	REV.NUM.	DESCRIPTION	ENG
11/16/2012	1	Initial Issue	АМ
10/24/2013	2	Update the flowchart	VZ

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Part description: High Sp	eed Edge Card Assembly

CERTIFICATION

All instruments and measuring equipment were calibrated to National Institute for Standards and Technology (NIST) traceable standards according to ISO 10012-1 and ANSI/NCSL 2540-1, as applicable.

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SCOPE

To perform the following tests: Design Qualification Test, Please see test plan

APPLICABLE DOCUMENTS

Standards: EIA Publication 364

TEST SAMPLES AND PREPARATION

- 1) All materials were manufactured in accordance with the applicable product specification.
- 2) All test samples were identified and encoded to maintain traceability throughout the test sequences.
- 3) After soldering, the parts to be used for LLCR and DWV/IR testing were cleaned according to TLWI-0001.
- 4) Either an automated cleaning procedure or an ultrasonic cleaning procedure may be used.
- 5) The automated procedure is used with aqueous compatible soldering materials.
- 6) Parts not intended for testing LLCR and DWV/IR are visually inspected and cleaned if necessary.
- 7) Any additional preparation will be noted in the individual test sequences.
- 8) Solder Information: Lead free
- 9) Re-Flow Time/Temp: See accompanying profile.
- 10) Samtec Test PCBs used: PCB-104046/PCB-104045/PCB-104049





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 Part description: High Speed Edge Card Assembly

FLOWCHARTS

Gas Tight

TEST	GROUP 1		
0755	8 Assemblies		
STEP	(.056" Thick Mating Card)		
01	LLCR-1		
02	Gas Tight		
03	LLCR-2		

Gas Tight = EA-364-36A

LLCR = EIA-364-23, LLCR

20 m V Max, 100 m A Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

Normal Force

TEST	GROUP 1	GROUP 2
STEP	(8 Contacts Minimum)	(8 Contacts Minimum) (.068" Thick Mating Card)
01	Contact Gaps	Contact Gaps
02	Setup Approved	Thermal Aging (Mated and Undisturbed)
03	Normal Force (in the body and soldered on PCB unless otherwise specified)	Contact Gaps
04		Setup Approved
05		Normal Force (in the body and soldered on PCB unless otherwise specified)

Thermal Aging = EIA-364-17, Test Condition 4 (105°C)

Time Condition 'B' (250 Hours)

Normal Force = EIA-364-04

(Perpendicular) Displacement Force = 12.7 mm/min ± 6 mm/min Spec is 50 N @ 1 mm displacement

Contact Gaps / Height - No standard method. Usually measured optically

Gaps to be taken on a minimum of 20% of each part tested

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FLOWCHARTS CONTINUED

Thermal Aging

TEST	GROUP 1	GROUP 2
STEP	8 Assemblies	8 Assemblies
	(.056" Thick Mating Card)	(.068" Thick Mating Card)
01	Contact Gaps	Contact Gaps
02	Forces - Mating / Unmating	Forces - Mating / Unmating
03	LLCR-1	LLCR-1
04	Thermal Aging (Mated and Undisturbed)	Thermal Aging (Mated and Undisturbed)
05	LLCR-2	LLCR-2
06	Forces - Mating / Unmating	Forces - Mating / Unmating
07	Contact Gaps	Contact Gaps

Thermal Aging = EIA-364-17, Test Condition 4 (105°C)

Time Condition 'B' (250 Hours)

Mating / Unmating Forces = EIA-364-13

Contact Gaps / Height - No standard method. Usually measured optically.

Gaps to be taken on a minimum of 20% of each part tested

LLCR = EIA-364-23, LLCR

20 m V Max, 100 m A Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

Current Carrying Capacity - Double Row

TEST	GROUP 1	GROUP 2	GROUP 3	GROUP 4	GROUP 5
STEP	3 Mated Assemblies				
	(.056" Thick Mating Card)				
01	CCC - 2 Contacts Powered	CCC - 4 Contacts Powered	CCC - 6 Contacts Powered	CCC - 8 Contacts Powered	CCC - All Contacts Powered

(TIN PLATING) - Tabulate calculated current at RT, 65°C, 75°C and 95°C after derating 20% and based on 105°C

(GOLD PLATING) - Tabulate calculated current at RT, 85°C, 95°C and 115°C

after derating 20% and based on 125°C

CCC, Temp rise = EIA-364-70

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Part description: High Speed Edge Card Assembly

FLOWCHARTS CONTINUED

Durability/Mating/Unmating/Gaps

TEST	GROUP 1	GROUP 2	GROUP 3	GROUP 4
	8 Assemblies	8 Assemblies	8 Assemblies	8 Assemblies
STEP	HSEC8-150-01-S-DV-A	HSEC8-150-01-S-DV-A	HSEC8-1100-01-S-DV-A	HSEC8-110-01-S-DV-A
	(.056" Thick Mating Card)	(.068" Thick Mating Card)	(.068" Thick Mating Card)	(.068" Thick Mating Card)
01	Contact Gaps	Contact Gaps	Contact Gaps	Contact Gaps
02	LLCR-1	LLCR-1	Forces - Mating / Unmating	Forces - Mating / Unmating
03	Forces - Mating / Unmating	Forces - Mating / Unmating	25 Cycles	25 Cycles
04	25 Cycles	25 Cycles	Forces - Mating / Unmating	Forces - Mating / Unmating
05	Forces - Mating / Unmating	Forces - Mating / Unmating	25 Cycles (50 Total)	25 Cycles (50 Total)
06	25 Cycles (50 Total)	25 Cycles (50 Total)	Forces - Mating / Unmating	Forces - Mating / Unmating
07	Forces - Mating / Unmating	Forces - Mating / Unmating	25 Cycles (75 Total)	25 Cycles (75 Total)
08	25 Cycles (75 Total)	25 Cycles (75 Total)	Forces - Mating / Unmating	Forces - Mating / Unmating
09	Forces - Mating / Unmating	Forces - Mating / Unmating	25 Cycles (100 Total)	25 Cycles (100 Total)
10	25 Cycles (100 Total)	25 Cycles (100 Total)	Forces - Mating / Unmating	Forces - Mating / Unmating
11	Forces - Mating / Unmating	Forces - Mating / Unmating		
12	Clean w/Compressed Air	Clean w/Compressed Air		
13	Contact Gaps	Contact Gaps		
14	LLCR-2	LLCR-2		
15	Thermal Shock (Mated and Undisturbed)	Thermal Shock (Mated and Undisturbed)		
16	LLCR-3	LLCR-3		
17	Cyclic Humidity (Mated and Undisturbed)	Cyclic Humidity (Mated and Undisturbed)		
18	LLCR-4	LLCR-4		
19	Forces - Mating / Unmating	Forces - Mating / Unmating		

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity = EIA-364-31, Test Condition B (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

Mating / Unmating Forces = EIA-364-13

Contact Gaps / $\ensuremath{\mathsf{Height}}$ - No standard method. Usually measured optically.

Gaps to be taken on a minimum of 20% of each part tested

LLCR = EA-364-23, LLCR

20 m V Max, 100 m A Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

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 Part description: High Speed Edge Card Assembly

<u>IR & D</u>	<u>& DWV</u>			
TEST	GROUP 1	GROUP 2	GROUP 3	GROUP 4
STEP	2 Mated Sets	2 Unmated of Part # Being Tested	2 Unmated of Mating Part #	2 Mated Sets
	Break Down Pin-to-Pin	Break Down Pin-to-Pin	Break Down Pin-to-Pin	Pin-to-Pin
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

FLOWCHARTS CONTINUED

TEST	GROUP 5	GROUP 6	GROUP 7	GROUP 8
STEP	2 Mated Sets	2 Unmated of Part # Being Tested	2 Unmated of Mating Part #	2 Mated Sets
	Break Down Row-to-Row	Break Down Row-to-Row	Break Down Row-to-Row	Row-to-Row
01	DWV/Break Down Voltage	DWV/Break Down Voltage	DWV/Break Down Voltage	IR & DWV at test voltage (on both mated sets and on each connector unmated)
02				Thermal Shock (Mated and Undisturbed)
03				IR & DWV at test voltage (on both mated sets and on each connector unmated)
04				Cyclic Humidity (Mated and Undisturbed)
05				IR & DWV at test voltage (on both mated sets and on each connector unmated)

DWV on Groups 4 and 8 to be performed at Test Voltage

DWV test voltage is equal to 75% of the lowest break down voltage

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity = EA-364-31, Test Condition B (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

IR = EIA-364-21

DWV = EIA-364-20, Test Condition 1

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FLOWCHARTS CONTINUED

Mechanical Shock / Vibration / LLCR

TEST	GROUP 1	GROUP 2
STEP	8 Assemblies (.056" Thick Mating Card)	8 Assemblies (.068" Thick Mating Card)
01	LLCR-1	LLCR-1
02	Shock	Shock
03	Vibration	Vibration
04	LLCR-2	LLCR-2

Mechanical Shock = EIA 364-27 Half Sine,

100 g's, 6 milliSeconds (Condition "C") each axis

Vibration = EIA 364-28, Random Vibration

7.56 g RMS, Condition VB --- 2 hours/axis

LLCR = EIA-364-23, LLCR

20 mV Max, 100 mA Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

Shock / Vibration / nanoSecond Event Detection

TEST	GROUP 1	
STEP	60 Points (.056" Thick Mating Card)	
01	Event Detection, Shock	
02	Event Detection, Vibration	

Mechanical Shock = EIA 364-27 Half Sine,

100 g's, 6 milliSeconds (Condition "C") each axis

Vibration = EA 364-28, Random Vibration

7.56 g RMS, Condition VB --- 2 hours/axis

Event detection requirement during Shock / Vibration is 50 nanoseconds minimum

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FLOWCHARTS CONTINUED

Extended Life

TEST	GROUP 1	GROUP 2	GROUP 3
	8 Assemblies	8 Assemblies	8 Assemblies
STEP	HSEC8-150-01-S-DV-A	HSEC8-150-01-S-DV-A	HSEC8-150-01-S-DV-A
	(.068 " Thick Mating Card)	(.068" Thick Mating Card)	(.068" Thick Mating Card)
	250 Cycles	500 Cycles	1,000 Cycles
01	* Plating Thickness	* Plating Thickness	* Plating Thickness
01	Verification	Verification	Verification
02	LLCR-1	LLCR-1	LLCR-1
03	250 Cycles	500 Cycles	1,000 Cycles
04	Clean Mating Interface	Clean Mating Interface	Clean Mating Interface
05	LLCR-2	LLCR-2	LLCR-2
06	Thermal Shock	Thermal Shock	Thermal Shock
00	(Mated and undisturbed)	(Mated and undisturbed)	(Mated and undisturbed)
07	LLCR-3	LLCR-3	LLCR-3
08	Cyclic Humidity	Cyclic Humidity	Cyclic Humidity
00	(Mated and undisturbed)	(Mated and undisturbed)	(Mated and undisturbed)
09	LLCR-4	LLCR-4	LLCR-4
10	*** Photos of Contact Area	*** Photos of Contact Area	*** Photos of Contact Area

Thermal Shock = EIA-364-32, Table II, Test Condition I:

-55°C to +85°C 1/2 hour dwell, 100 cycles

Humidity =EIA-364-31, Test Condition 'B' (240 Hours)

and Method III (+25°C to +65°C @ 90% RH to 98% RH)

ambient pre-condition and delete steps 7a and 7b

LLCR = EIA-364-23, LLCR

20 mV Max, 100 mA Max

Use Keithley 580 or 3706 in 4 wire dry circuit mode

* Measure, verify, and document plating thickness on both male and female (one group only)

** Plating thickness to be measured on loose pins used during assembly. Pins to be provided by requestor.

*** Save 2-3 photos of contact area in project folder for each group

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Part description: High Speed Edge Card Assembly

ATTRIBUTE DEFINITIONS

The following is a brief, simplified description of attributes.

THERMAL AGE:

- 1) EIA-364-17, Temperature Life with or without Electrical Load Test Procedure for Electrical Connectors.
- 2) Test Condition 4 at 105° C.
- 3) Test Time Condition B for 250 hours.
- 4) All test samples are pre-conditioned at ambient.
- 5) All test samples are exposed to environmental stressing in the mated condition.

THERMAL SHOCK:

- 1) EIA-364-32, Thermal Shock (Temperature Cycling) Test Procedure for Electrical Connectors.
- 2) Test Condition 1: -55°C to +85°C
- 3) Test Time: $\frac{1}{2}$ hour dwell at each temperature extreme
- 4) Number of Cycles: 100
- 5) All test samples are pre-conditioned at ambient.
- 6) All test samples are exposed to environmental stressing in the mated condition.

HUMIDITY:

- 1) Reference document: EIA-364-31, Humidity Test Procedure for Electrical Connectors.
- 2) Test Condition B, 240 Hours.
- 3) Method III, +25° C to + 65° C, 90% to 98% Relative Humidity excluding sub-cycles 7a and 7b.
- 4) All samples are pre-conditioned at ambient.
- 5) All test samples are exposed to environmental stressing in the mated condition.

MECHANICAL SHOCK (Specified Pulse):

- 1) Reference document: EIA-364-27, Mechanical Shock Test Procedure for Electrical Connectors
- 2) Test Condition C
- 3) Peak Value: 100 G
- 4) Duration: 6 Milliseconds
- 5) Wave Form: Half Sine
- 6) Velocity: 12.3 ft/s
- 7) Number of Shocks: 3 Shocks / Direction, 3 Axis (18 Total)

VIBRATION:

- 1) Reference document: EIA-364-28, Vibration Test Procedure for Electrical Connectors
- 2) Test Condition V, Letter B
- 3) Power Spectral Density: 0.04 G² / Hz
- 4) G 'RMS': 7.56
- 5) Frequency: 50 to 2000 Hz
- 6) Duration: 2.0 Hours per axis (3 axis total)

NANOSECOND-EVENT DETECTION:

- 1) Reference document: EIA-364-87, Nanosecond-Event Detection for Electrical Connectors
- 2) Prior to test, the samples were characterized to assure the low nanosecond event being monitored will trigger the detector.
- 3) After characterization it was determined the test samples could be monitored for 50 nanosecond events

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ATTRIBUTE DEFINITIONS Continued

The following is a brief, simplified description of attributes

MATING/UNMATING:

- 1) Reference document: EIA-364-13, Mating and Unmating Forces Test Procedure for Electrical Connectors.
- 2) The full insertion position was to within 0.003" to 0.004" of the plug bottoming out in the receptacle to prevent damage to the system under test.
- 3) One of the mating parts is secured to a floating X-Y table to prevent damage during cycling.

NORMAL FORCE (FOR CONTACTS TESTED IN THE HOUSING):

- 1) The test shall be performed in accordance with EIA-364-13D, Mating and EIA-364-04A, Normal Force Test Procedure for Electrical Connectors.
- 2) The contacts shall be tested in the connector housing and soldered to a PCB.
- 3) If necessary, a "window" shall be made in the connector body to allow a probe to engage and deflect the contact at the same attitude and distance (plus 0.05 mm [0.002"]) as would occur in actual use.
- 4) The connector housing shall be placed in a holding fixture that does not interfere with or otherwise influence the contact force or deflection.
- 5) Said holding fixture shall be mounted on a floating, adjustable, X-Y table on the base of the computer controlled test stand interconnected to the force-deflection measurement system.
- 6) The nominal deflection rate shall be 5 mm $(0.2^{"})$ /minute.
- 7) Unless otherwise noted a minimum of five contacts shall be tested.
- 8) The force/deflection characteristic to load and unload each contact shall be repeated five times.
- 9) The permanent set of each contact shall be measured based on the initial zero point versus the final zero point.
- 10) The acquired data shall be graphed in accordance with EIA-364-04A, ¶ 4.1.1.6 to 4.1.1.7.

TEMPERATURE RISE (Current Carrying Capacity, CCC):

1) EIA-364-70, Temperature Rise versus Current Test Procedure for Electrical Connectors and Sockets.

- 2) When current passes through a contact, the temperature of the contact increases as a result of I^2R (resistive) heating.
- 3) The number of contacts being investigated plays a significant part in power dissipation and therefore temperature rise.
- 4) The size of the temperature probe can affect the measured temperature.
- 5) Copper traces on PC boards will contribute to temperature rise:
 - a. Self heating (resistive)
 - b. Reduction in heat sink capacity affecting the heated contacts
- 6) A de-rating curve, usually 20%, is calculated.
- 7) Calculated de-rated currents at three temperature points are reported:
 - a. Ambient
 - b. 80[°] C
 - c. 95[°] C
 - d. 115° C
 - d. 115 C
- 8) Typically, neighboring contacts (in close proximity to maximize heat build up) are energized.
- 9) The thermocouple (or temperature measuring probe) will be positioned at a location to sense the maximum temperature in the vicinity of the heat generation area.
- 10) A computer program, TR 803.exe, ensures accurate stability for data acquisition.
- 11) Hook-up wire cross section is larger than the cross section of any connector leads/PC board traces, jumpers, etc.
- 12) Hook-up wire length is longer than the minimum specified in the referencing standard.

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ATTRIBUTE DEFINITIONS Continued

The following is a brief, simplified description of attributes

LLCR:

- 1) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 2) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 3) The following guidelines are used to categorize the changes in LLCR as a result from stressing
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms: ----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms: ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

GAS TIGHT:

To provide method for evaluating the ability of the contacting surfaces in preventing penetration of harsh vapors which might lead to oxide formation that may degrade the electrical performance of the contact system.

- 1) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 2) A computer program, LLCR 221.exe, ensures repeatability for data acquisition.
- 3) The following guidelines are used to categorize the changes in LLCR as a result from stressing
 - a. <= +5.0 mOhms:----- Stable
 - b. +5.1 to +10.0 mOhms: ----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms:----- Unstable
 - f. >+2000 mOhms: ----- Open Failure
- 4) Procedure:
 - a. Reference document: EIA-364-36, *Test Procedure for Determination of Gas-Tight Characteristics for Electrical Connectors, Sockets and/or Contact Systems.*
 - b. Test Conditions:
 - i. Class II--- Mated pairs of contacts assembled to their plastic housings.
 - ii. Reagent grade Nitric Acid shall be used of sufficient volume to saturate the test chamber
 - iii. The ratio of the volume of the test chamber to the surface area of the acid shall be 10:1.
 - iv. The chamber shall be saturated with the vapor for at least 15 minutes before samples are added.
 - v. Exposure time, 55 to 65 minutes.
 - vi. The samples shall be no closer to the chamber walls than 1 inches and no closer to the surface of the acid than 3 inches.
 - vii. The samples shall be dried after exposure for a minimum of 1 hour.
 - viii. Drying temperature 50° C
 - ix. The final LLCR shall be conducted within 1 hour after drying.

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ATTRIBUTE DEFINITIONS Continued

The following is a brief, simplified description of attributes

INSULATION RESISTANCE (IR):

To determine the resistance of insulation materials to leakage of current through or on the surface of these materials when a DC potential is applied.

- 1) PROCEDURE:
 - a. Reference document: EIA-364-21, *Insulation Resistance Test Procedure for Electrical Connectors*.b. Test Conditions:
 - i. Between Adjacent Contacts or Signal-to-Ground
 - ii. Electrification Time 2.0 minutes
 - iii. Test Voltage (500 VDC) corresponds to calibration settings for measuring resistances.
- 2) MEASUREMENTS:
- 3) When the specified test voltage is applied (VDC), the insulation resistance shall not be less than 1000 megohms.

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

To determine if the sockets can operate at its rated voltage and withstand momentary over potentials due to switching, surges, and other similar phenomenon. Separate samples are used to evaluate the effect of environmental stresses so not to influence the readings from arcing that occurs during the measurement process.

- 1) PROCEDURE:
 - a. Reference document: EIA-364-20, Withstanding Voltage Test Procedure for Electrical Connectors.
 - b. Test Conditions:
 - i. Between Adjacent Contacts or Signal-to-Ground
 - ii. Barometric Test Condition 1
 - iii. Rate of Application 500 V/Sec
 - iv. Test Voltage (VAC) until breakdown occurs
- 2) MEASUREMENTS/CALCULATIONS
 - a. The breakdown voltage shall be measured and recorded.
 - b. The dielectric withstanding voltage shall be recorded as 75% of the minimum breakdown voltage.
 - c. The working voltage shall be recorded as one-third (1/3) of the dielectric withstanding voltage (one-fourth of the breakdown voltage).

emperature Ris	Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A
emperature Ris	Part description:	High Speed Edge Card Assembly
emperature Ris		
emperature Ris		RESULTS
	e, CCC at a 20% de-rating	
		2.8A per contact with 2 adjacent contacts powered
	-	2.2A per contact with 4 adjacent contacts powered 1.9A per contact with 6 adjacent contacts powered
	-	
	-	1.0A per contact with all adjacent contacts powered
	· · · · · · · · · · · · · · · · · · ·	F
lating – Unmati	ing Forces	
harmal Aga (HSI	EC8-150-01-S-DV-A/ 0.056" E	dae Card)
• Initial	2C0-130-01-5-D V-A/ 0.050 E	ige Caru)
o Ma	ting	
	• Min	
	• Max	10.68 Lbs
o Uni	nating	
	 Min Max 	
• After Thern		5.10 LD8
• Alter mern		
0 1014	• Min	5.45 Lbs
	• Max	
o Uni	nating	
	• Min	
	• Max	2.90 Lbs
houmal A ao (USI	EC8-150-01-S-DV-A/ 0.068" E	dae Cond)
• Initial	2C0-130-01-3-D V-A/ 0.000 E	ige Calu
• Initial • Ma	ting	
0 1014	• Min	12.46 Lbs
	• Max	
o Uni	nating	
	• Min	
	• Max	6.65 Lbs
After Therm		
o Ma	ting Min 	0.30 L bs
	 Max 	
o Uni	nating	
	• Min	3.35 Lbs
	• Max	3.85 Lbs

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Part description: H	ligh Speed Edge Card Assembly
RESU	JLTS Continued
lating/Unmating Durability (HSEC8-150-01-S-DV-A/	/ 0.056" Edge Card)
• Initial	
• Mating	
• Min	
• Max	9.57 Lbs
 Unmating Min 	2 87 I bs
• Max	
	4.18 L08
After 25 Cycles Mating	
 Mating Min 	8 04 L bs
• Max	
• Unmating	
 Min 	3.45 Lbs
• Max	
After 50 Cycles	
• Mating	
• Min	7.83 Lbs
• Max	9.88 Lbs
• Unmating	
• Min	4.07 Lbs
• Max	5.44 Lbs
After 75 Cycles	
• Mating	
• Min	
• Max	9.88 Lbs
• Unmating	
 Min Max 	
	0.28 LD8
After 100 Cycles Mating	
 Mating Min 	8 11 I be
 Max 	
• Unmating	10:00 100
• Min	5.12 Lbs
• Max	
• Humidity	
• Mating	
• Min	4.54 Lbs
• Max	5.43 Lbs
• Unmating	
• Min	1.82 Lbs
• Max	2.25 Lbs

Tracking Code: 218303 Report Rev 2 Part #: HSEC8-150-01-S-DV-A Part description: High Speed Edge Card Assembly **RESULTS Continued** Mating/Unmating Durability (HSEC8-150-01-S-DV-A/ 0.068" Edge Card) Initial • 0 Mating Min -----10.33 Lbs . Max-----14.04 Lbs . Unmating 0 Min ----- 4.07 Lbs Max----- 5.30 Lbs . After 25 Cycles Mating 0 Min -----10.92 Lbs Max-----13.80 Lbs . Unmating 0 Min ----- 4.90 Lbs Max-----7.55 Lbs . After 50 Cycles Mating 0 Min -----11.27 Lbs Max-----13.78 Lbs . Unmating 0 Min ----- 5.35 Lbs Max----- 8.26 Lbs -After 75 Cycles Mating 0 Min -----11.50 Lbs Max-----14.01 Lbs 0 Unmating Min ----- 5.93 Lbs Max----- 8.52 Lbs -After 100 Cycles Mating 0 Min -----11.34 Lbs Max-----14.43 Lbs Unmating 0 Min ----- 6.10 Lbs Max-----9.03 Lbs Humidity • Mating 0 Min ----- 6.77 Lbs Max-----7.54 Lbs Unmating 0 Min ----- 2.40 Lbs Max------ 3.14 Lbs

Tracking Code: 218303 Report Rev 2 Part #: HSEC8-150-01-S-DV-A Part description: High Speed Edge Card Assembly **RESULTS Continued** Mating/Unmating Basic (HSEC8-1100-01-S-DV-A/0.068" Edge Card) Initial 0 Mating Min -----16.86 Lbs . Max-----21.57 Lbs • Unmating 0 Min ----- 7.30 Lbs Max-----9.27 Lbs . After 25 Cycles Mating 0 Min -----20.28 Lbs Max-----27.38 Lbs . Unmating 0 Min ------10.06 Lbs . Max-----15.25 Lbs . After 50 Cycles Mating 0 Min ----------20.63 Lbs Max-----29.06 Lbs -Unmating 0 Min -----10.74 Lbs Max-----17.58 Lbs -After 75 Cycles Mating 0 Min -----20.93 Lbs Max-----29.57 Lbs . 0 Unmating Min -----11.35 Lbs Max-----19.65 Lbs -After 100 Cycles Mating 0 Min -----21.28 Lbs Max-----30.24 Lbs Unmating 0 Min -----11.50 Lbs Max-----21.18 Lbs

king Code: 218303_Report_Rev 2		#: HSEC8-150-01-S-DV-A
Part description: Hi	igh Speed Edge Card Assem	bly
RES	SULTS Continued	
Basia (HEECO 110 01 6 DV 4/0 000	"Edge Cond)	
ig Basic (HSEC8-110-01-S-DV-A/0.068)	" Edge Card)	
Mating		
	1.64 L.bs	
	0.79 Lbs	
• Max	1.10 Lbs	
5 Cycles		
	3.07 Lbs	
	1 07 I ba	
•		
	1.76 Lbs	
	1.59 Lbs	
•		
8	1 75 1 1	
	3.1 / LDS	
	1 33 L.bs	
•		
	1.76 Lbs	
• Max	3.03 Lbs	
Unmating		
• Max	1.91 Lbs	
	ng Basic (HSEC8-110-01-S-DV-A/0.068 Mating Max	mg Basic (HSEC8-110-01-S-DV-A/0.068" Edge Card) Mating • Min • Max 3.47 Lbs Unmating • Min • Min • Min • Min • Max • Min • Min • Min • Max • Max • Min • Max • Min • Max • Max<

		0	
0	Max	56.90 gf	

Tracking Code: 218303_Report_Rev 2 Part #: HSEC8-150-01-S-DV-A Part description: High Speed Edge Card Assembly **RESULTS** Continued Insulation resistance minimums, IR Initial • Mated -----Pass Unmated-----Pass District Content of C \cap 0 Thermal ------Mated------Pass 0 Unmated------Pass 0 Humidity Mated-----Pass 0 Unmated-----Pass 0 **Dielectric Withstanding Voltage minimums, DWV** Minimums Breakdown Voltage------960 VAC 0 Test Voltage ------ 720 VAC 0 Working Voltage ----- 240 VAC 0 Initial DWV ----- Passed Thermal DWV------ Passed Humidity----- Passed LLCR Gas Tight (192 LLCR test points) HSEC8-150-01-S-DV-A/ 0.056" Edge Card Initial -----7.81 mOhms Max **Gas Tight** • o <= +5.0 mOhms ------ 192 Points ------ Stable +5.1 to +10.0 mOhms ------ 0 Points ----- 0 Minor 0 +10.1 to +15.0 mOhms ------ 0 Points ------ Acceptable 0 +15.1 to +50.0 mOhms ------ 0 Points ------ Marginal 0 +50.1 to +2000 mOhms------ Unstable 0 >+2000 mOhms------ Open Failure 0 LLCR Thermal Age (192 LLCR test points) HSEC8-150-01-S-DV-A/0.056" Edge Card -----7.74 mOhms Max Initial ----**Thermal Age** <= +5.0 mOhms ------ Stable</p> 0 +5.1 to +10.0 mOhms ------ 21 Points ------ Minor 0 +10.1 to +15.0 mOhms ------ 1 Points ------ Acceptable 0 +15.1 to +50.0 mOhms ------ 0 Points ------ 0 Marginal 0 +50.1 to +2000 mOhms------ Unstable 0 >+2000 mOhms------ Open Failure 0 LLCR Thermal Age (192 LLCR test points) HSEC8-150-01-S-DV-A/0.068" Edge Card -----6.24 mOhms Max Initial ----. **Thermal Age** • <= +5.0 mOhms ------ 192 Points ------ Stable +5.1 to +10.0 mOhms ------ 0 Points ----- 0 Minor 0 +10.1 to +15.0 mOhms ------ 0 Points ------ Acceptable 0 0 +50.1 to +2000 mOhms------- Unstable 0

Part description: High Speed Edge Card Assembly **RESULTS Continued** LLCR Mate/Unmate Durability (192 LLCR test points) HSEC8-150-01-S-DV-A/ 0.056" Edge Card ----- 7.83 mOhms Max Initial -----**Durability, 100 Cycles** <= +5.0 mOhms ------ Stable</p> 0 +5.1 to +10.0 mOhms ------ 0 Points ----- 0 Minor 0 +10.1 to +15.0 mOhms ------ 0 Points ------ Acceptable 0 +15.1 to +50.0 mOhms ------ 0 Points ------ Marginal 0 +50.1 to +2000 mOhms------ 0 Points ------ Unstable 0 >+2000 mOhms------ Open Failure 0 **Thermal Shock** <= +5.0 mOhms ------ 192 Points ------ Stable 0 +5.1 to +10.0 mOhms -------0 Points ------ 0 Points ------ Minor +10.1 to +15.0 mOhms ------ 0 Points ------ Acceptable 0 0 +15.1 to +50.0 mOhms ------ 0 Points ------ Marginal 0 +50.1 to +2000 mOhms------ Unstable 0 >+2000 mOhms------ Open Failure 0 Humidity <= +5.0 mOhms ------ 191 Points ------ Stable 0 +5.1 to +10.0 mOhms ------ Minor 0 +10.1 to +15.0 mOhms ------ 0 Points ------ Acceptable 0 +15.1 to +50.0 mOhms ------ 0 Points ------ Marginal 0 +50.1 to +2000 mOhms------0 Points ------ Unstable >+2000 mOhms------ 0 Points ------ Open Failure 0 0

Part #: HSEC8-150-01-S-DV-A

Tracking Code: 218303 Report Rev 2

LLCR Mate/Unmate Durability (192 LLCR test points)

HSEC8-150-01-S-DV-A/ 0.068" Edge Card

Initial		5.87 mOhms Max	
Durab	ility, 100 Cycles		
0	<= +5.0 mOhms	191 Points	Stable
0	+5.1 to +10.0 mOhms	1 Points	Minor
0	+10.1 to +15.0 mOhms	0 Points	Acceptable
0	+15.1 to +50.0 mOhms	0 Points	Marginal
0	+50.1 to +2000 mOhms	0 Points	Unstable
0	>+2000 mOhms	0 Points	Open Failure
Therm	al		
0	<= +5.0 mOhms	192 Points	Stable
0	+5.1 to +10.0 mOhms	0 Points	Minor
0	+10.1 to +15.0 mOhms	0 Points	Acceptable
0	+15.1 to +50.0 mOhms	0 Points	Marginal
0	+50.1 to +2000 mOhms	0 Points	Unstable
0	>+2000 mOhms	0 Points	Open Failure
Humid	lity		
0	<= +5.0 mOhms	191 Points	Stable
0	+5.1 to +10.0 mOhms	1 Points	Minor
0	+10.1 to +15.0 mOhms	0 Points	Acceptable
0	+15.1 to +50.0 mOhms	0 Points	Marginal
0		0 Points	0
0		0 Points	

Tracking Code: 218303_Report_Rev 2 Part #: HSEC8-150-01-S-DV-A
Part description: High Speed Edge Card Assembly
RESULTS Continued
LLCR Mechanical Shock & Random Vibration (192 LLCR test points)
HSEC8-150-01-S-DV-A/ 0.056" Edge Card
• Initial8.29 mOhms Max
Mechanical Shock & Random Vibration
o <= +5.0 mOhms 192 Points Stable
• +5.1 to +10.0 mOhms0 Points0 Points

- +10.1 to +15.0 mOhms ------ 0 Points ----- 0 Points ----- Acceptable
 +15.1 to +50.0 mOhms ------ 0 Points ------ 0 Points ------ Marginal
- +50.1 to +2000 mOhms-------0 Points ------ Unstable
- o >+2000 mOhms ------ Open Failure

-----6.42 mOhms Max

HSEC8-150-01-S-DV-A/ 0.068" Edge Card

Initial ------

- Mechanical Shock & Random Vibration

Mechanical Shock & Random Vibration Event Detection

HSEC8-150-01-S-DV-A/ 0.056" Edge Card

• Shock

UIX.		
0	No Damage	-Passed
0	50 Nanoseconds	-Passed

• Vibration

No Damage -----Passed
 50 Nanoseconds -----Passed

 Tracking Code: 218303
 Report_Rev 2
 Part #: HSEC8-150-01-S-DV-A

 Part description: High Speed Edge Card Assembly

	RES	ULTS Continued	
	ndad I ifa 750 Gualas (107 I I CD	tost noints)	
	nded Life 250 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card	(test points)	
		6.08 mOhms Max	
	bility, 250 Cycles		
0	<= +5.0 mOhms	192 Points	Stable
0	+5.1 to +10.0 mOhms		
0	+10.1 to +15.0 mOhms	0 Points	Acceptable
0	+15.1 to +50.0 mOhms	0 Points	Marginal
0	+50.1 to +2000 mOhms	0 Points	Unstable
0	>+2000 mOhms	0 Points	Open Failure
• Thern	nal		
0			
0	+5.1 to +10.0 mOhms		
0	+10.1 to +15.0 mOhms		
0	+15.1 to +50.0 mOhms		8
0	+50.1 to +2000 mOhms		
0	>+2000 mOhms	0 Points	Open Failure
• Humi			
0			
0	+5.1 to +10.0 mOhms		
0	+10.1 to +15.0 mOhms		
0	+15.1 to +50.0 mOhms		
0	+50.1 to +2000 mOhms	0 Points	Unstable
			0 5 1
0	>+2000 mOhms		Open Failure
-		0 Points	Open Failure
LCR Exte	nded Life 500 Cycles (192 LLCR	0 Points	Open Failure
LCR Extense SEC8-150-01	nded Life 500 Cycles (192 LLCR 1-S-DV-A/ 0.068" Edge Card	0 Points test points)	Open Failure
LCR Exter SEC8-150-01 • Initial	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card	0 Points test points)	Open Failure
LCR Exter SEC8-150-01 • Initial • Durat	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card I Dility, 500 Cycles	0 Points test points) 6.32 mOhms Max	·
LCR Exter SEC8-150-01 • Initial • Durat °	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points) 6.32 mOhms Max 192 Points	Stable
LCR Exter SEC8-150-01 • Initial • Durat ° •	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points) 6.32 mOhms Max 192 Points	Stable Minor
LCR Exter SEC8-150-01 • Initial • Durat • • • • • • • • • • • • • • • •	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card I	0 Points 2 test points) 6.32 mOhms Max 192 Points 0 Points	Stable Minor Acceptable
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points) 6.32 mOhms Max 0 Points 0 Points 0 Points 0 Points	Stable Minor Acceptable Marginal
LCR Exter SEC8-150-01 • Initial • Durat • • • • • • • • • • • • • • • • • • •	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points) 6.32 mOhms Max 0 Points 0 Points 0 Points 0 Points 0 Points 0 Points	Stable Minor Acceptable Marginal Unstable
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points) 6.32 mOhms Max 0 Points 0 Points 0 Points 0 Points 0 Points 0 Points	Stable Minor Acceptable Marginal Unstable
LCR Exter SEC8-150-01 • Initial • Durat • • • • • • • • • • • • • • • • • • •	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points) 6.32 mOhms Max 0 Points 0 Points 0 Points 0 Points 0 Points 0 Points	Stable Minor Acceptable Marginal Unstable Open Failure
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Therm • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points) 6.32 mOhms Max 0 Points 0 Points 0 Points 0 Points 0 Points 0 Points	Stable Minor Acceptable Marginal Unstable Open Failure
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Therm • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 		Stable Minor Acceptable Marginal Unstable Open Failure Stable Stable
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Therm • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 		Stable Minor Acceptable Marginal Unstable Open Failure Stable Stable Acceptable
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Therm • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points)	Stable Minor Marginal Unstable Open Failurc Stable Stable Acceptable Marginal
LCR Exter SEC8-150-01 • Initial • Durat • O • O • Therm • O • O	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points)	Stable Minor Acceptable Marginal Unstable Open Failure Stable Minor Acceptable Marginal Unstable
LCR Exter SEC8-150-01 • Initial • Durat • O • O • Therm • O • O • O • O	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points)	Stable Minor Acceptable Marginal Unstable Open Failure Stable Minor Acceptable Marginal Unstable
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Therm • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points)	Stable Minor Acceptable Marginal Unstable Open Failure Stable Minor Acceptable Marginal Unstable Open Failure
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Thern • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 		Stable Minor Acceptable Marginal Unstable Open Failure Stable Minor Minor Minor Minor Stable Open Failure
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Therm • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 		Stable Minor Acceptable Marginal Unstable Open Failure Stable Marginal Unstable Open Failure Stable Stable
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Thern • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 		Stable Minor Acceptable Marginal Unstable Open Failure Stable Marginal Unstable Open Failure Stable Stable Stable
LCR Exter SEC8-150-01 • Initial • Durat • 0 • 0 • Therm • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0 • 0	nded Life 500 Cycles (192 LLCR I-S-DV-A/ 0.068" Edge Card 	0 Points 2 test points)	Stable Minor Acceptable Marginal Unstable Open Failure Stable Marginal Open Failure Stable Stable Stable Stable Acceptable Marginal

Tracking Code: 218303_Report_Rev 2 Part #: HSEC8-150-01-S-DV-A

Part description: High Speed Edge Card Assembly

RESULTS Continued

LLCR Extended Life 1000 Cycles (192 LLCR test points) HSEC8-150-01-S-DV-A/ 0.068" Edge Card

-----5.91 mOhms Max Initial ---- Development 1000 Cycle

٠	Durabi	ility, 1000 Cycles		
	0	<= +5.0 mOhms	192 Points	Stable
	0	+5.1 to +10.0 mOhms	0 Points	Minor
	0		0 Points	
	0		0 Points	
	0	+50.1 to +2000 mOhms	0 Points	Unstable
	0	>+2000 mOhms	0 Points	Open Failure
•	Therm	al		-
	0		192 Points	
	0		0 Points	
	0	+10.1 to +15.0 mOhms	0 Points	Acceptable
	0	+15.1 to +50.0 mOhms	0 Points	Marginal
	0	+50.1 to +2000 mOhms	0 Points	Unstable
	0	>+2000 mOhms	0 Points	Open Failure
•	Humid	ity		-
	0	<= +5.0 mOhms	189 Points	Stable
	0	+5.1 to +10.0 mOhms	3 Points	Minor
	0	+10.1 to +15.0 mOhms	0 Points	Acceptable
	0	+15.1 to +50.0 mOhms	0 Points	Marginal
	0	+50.1 to +2000 mOhms	0 Points	Unstable
	0	>+2000 mOhms	0 Points	Open Failure

 Tracking Code: 218303_Report_Rev 2
 Part #: HSEC8-150-01-S-DV-A

 Part description: High Speed Edge Card Assembly

DATA SUMMARIES

TEMPERATURE RISE (Current Carrying Capacity, CCC):

1) High quality thermocouples whose temperature slopes track one another were used for temperature monitoring.

2) The thermocouples were placed at a location to sense the maximum temperature generated during testing.3) Temperature readings recorded are those for which three successive readings, 15 minutes apart, differ less

than 1° C (computer controlled data acquisition).

4) Adjacent contacts were powered:

a. Two adjacent conductors/contacts powered







Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A				
Part description: High Speed Edge Card Assembly					

MATING-UNMATING FORCES

Thermal Age HSEC8-150-01-S-DV-A/ 0.056" Edge Card

	Initial				After Thermals			
	Mating		Unmating		Mating		Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	29.67	6.67	13.08	2.94	24.24	5.45	9.87	2.22
Maximum	47.50	10.68	22.68	5.10	32.07	7.21	12.90	2.90
Average	42.32	9.51	19.71	4.43	30.08	6.76	11.49	2.58
St Dev	5.84	1.31	3.08	0.69	2.79	0.63	1.00	0.23
Count	8	8	8	8	8	8	8	8

Thermal Age HSEC8-150-01-S-DV-A/ 0.068" Edge Card

		Initial				After Thermals			
	Mating		Unmating		Mating		Unmating		
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	
Minimum	55.42	12.46	18.64	4.19	41.37	9.30	14.90	3.35	
Maximum	71.26	16.02	29.58	6.65	46.13	10.37	17.12	3.85	
Average	65.73	14.78	25.29	5.69	43.57	9.80	15.78	3.55	
St Dev	5.14	1.16	3.70	0.83	1.74	0.39	0.81	0.18	
Count	8	8	8	8	8	8	8	8	

Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A					
Part description: High Speed Edge Card Assembly						

Mating/Unmating Durability HSEC8-150-01-S-DV-A/ 0.056" Edge Card

	Initial				25 Cycles			
	Mat	ing	Unmating		Mat	ing	Unm	ating
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	33.14	7.45	12.77	2.87	35.76	8.04	15.35	3.45
Maximum	42.57	9.57	18.59	4.18	42.79	9.62	21.44	4.82
Average	38.33	8.62	16.69	3.75	39.67	8.92	19.64	4.42
St Dev	2.65	0.60	1.82	0.41	2.26	0.51	1.97	0.44
Count	8	8	8	8	8	8	8	8
		50 C	ycles			75 C	ycles	
	Mat	ing	Unm	ating	Mat	ing	Unm	ating
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	34.83	7.83	18.10	4.07	34.29	7.71	20.37	4.58
Maximum	43.95	9.88	24.20	5.44	43.95	9.88	27.93	6.28
Average	39.73	8.93	22.40	5.04	39.78	8.94	24.71	5.56
St Dev	2.69	0.60	1.98	0.44	2.83	0.64	2.29	0.52
Count	8	8	8	8	8	8	8	8
		100 C	ycles		After Humidity			
	Mat	ing	Unm	ating	Mating		Unm	ating
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	36.07	8.11	22.77	5.12	20.19	4.54	8.10	1.82
Maximum	44.70	10.05	30.74	6.91	24.15	5.43	10.01	2.25
Average	40.25	9.05	27.15	6.10	21.43	4.82	8.96	2.02
St Dev	2.65	0.59	2.54	0.57	1.23	0.28	0.63	0.14
Count	8	8	8	8	8	8	8	8

Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A					
Part description: High Speed Edge Card Assembly						

Mating/Unmating Durability HSEC8-150-01-S-DV-A/ 0.068" Edge Card

		Initial				25 Cycles			
	Mat	ing	Unmating		Mat	ing	Unmating		
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	
Minimum	45.95	10.33	18.10	4.07	48.57	10.92	21.80	4.90	
Maximum	62.45	14.04	23.57	5.30	61.38	13.80	33.58	7.55	
Average	53.61	12.05	20.92	4.70	55.59	12.50	25.84	5.81	
St Dev	5.83	1.31	2.21	0.50	4.07	0.91	3.72	0.84	
Count	8	8	8	8	8	8	8	8	
		50 C	ycles			75 C	ycles		
	Mat	ing	Unm	ating	Mat	ing	Unm	ating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	
Minimum	50.13	11.27	23.80	5.35	51.15	11.50	26.38	5.93	
Maximum	61.29	13.78	36.74	8.26	62.32	14.01	37.90	8.52	
Average	56.80	12.77	28.60	6.43	57.47	12.92	31.47	7.08	
St Dev	3.92	0.88	4.08	0.92	3.86	0.87	4.05	0.91	
Count	8	8	8	8	8	8	8	8	
		100 C	ycles		After Humidity				
	Mat	ing	Unm	ating	Mating		Unm	ating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	
Minimum	50.44	11.34	27.13	6.10	30.11	6.77	10.68	2.40	
Maximum	64.18	14.43	40.17	9.03	33.54	7.54	13.97	3.14	
Average	58.27	13.10	33.80	7.60	31.48	7.08	11.66	2.62	
St Dev	4.41	0.99	4.33	0.97	1.30	0.29	1.05	0.24	
Count	8	8	8	8	8	8	8	8	

Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A					
Part description: High Speed Edge Card Assembly						

Mating/Unmating Basic HSEC8-1100-01-S-DV-A/ 0.068" Edge Card

13.30

8

St Dev

Count

2.99

8

14.73

8

		Ini	tial		25 Cycles			
	Ma	ting	Unmating		Mating		Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	74.99	16.86	32.47	7.30	90.21	20.28	44.75	10.06
Maximum	95.94	21.57	41.23	9.27	121.79	27.38	67.83	15.25
Average	86.88	19.53	36.29	8.16	106.56	23.96	57.34	12.89
St Dev	7.88	1.77	2.93	0.66	12.85	2.89	7.39	1.66
Count	8	8	8	8	8	8	8	8
<u>.</u>	50 Cycles				75 C	ycles		
	Ma	ting	Unm	ating	Mat	ting	Unmating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)
Minimum	91.76	20.63	47.77	10.74	93.10	20.93	50.48	11.35
Maximum	129.26	29.06	78.20	17.58	131.53	29.57	87.40	19.65
Average	113.18	25.45	66.96	15.05	116.89	26.28	73.89	16.61
St Dev	13.26	2.98	10.10	2.27	13.40	3.01	12.34	2.77
Count	8	8	8	8	8	8	8	8
		100 C	ycles					
	Mating Unmating		ating					
	New tons	Force (Lbs)	New tons	Force (Lbs)				
Minimum	94.65	21.28	51.15	11.50				
Maximum	134.51	30.24	94.21	21.18				
Average	119.05	26.76	79.21	17.81				

3.31

8

Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A					
Part description: High Speed Edge Card Assembly						

Mating/Unmating Basic HSEC8-110-01-S-DV-A/ 0.068" Edge Card

		Ini	tial		25 Cycles				
	Mat	ing	Unm	ating	Mat	ing	Unm	ating	
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	
Minimum	7.29	1.64	3.51	0.79	7.47	1.68	4.76	1.07	
Maximum	15.43	3.47	4.89	1.10	13.66	3.07	6.54	1.47	
Average	9.22	2.07	4.15	0.93	10.01	2.25	5.72	1.29	
St Dev	2.60	0.58	0.54	0.12	1.80	0.40	0.59	0.13	
Count	8	8	8	8	8	8	8	8	
		50 C	ycles			75 C	ycles		
	Mat	ing	Unmating		Mating		Unmating		
	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	New tons	Force (Lbs)	
Minimum	7.83	1.76	5.43	1.22	7.78	1.75	5.92	1.33	
Maximum	18.28	4.11	7.07	1.59	14.10	3.17	8.10	1.82	
Average	10.99	2.47	6.29	1.41	10.69	2.40	6.84	1.54	
St Dev	3.14	0.71	0.62	0.14	1.80	0.41	0.78	0.17	
Count	8	8	8	8	8	8	8	8	
		100 C	ycles						
	Mat	ing	Unm	ating					
	New tons	Force (Lbs)	New tons	Force (Lbs)					
Minimum	7.83	1.76	5.78	1.30					
Maximum	13.48	3.03	8.50	1.91					
Average	10.73	2.41	7.14	1.61					
St Dev	1.66	0.37	1.01	0.23					
Count	8	8	8	8					





Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A
Part description: High Sp	eed Edge Card Assembly

NORMAL FORCE (FOR CONTACTS TESTED IN THE HOUSING):
1) Calibrated force gauges are used along with computer controlled positioning equipment.
2) For Normal force 8-10 measurements are taken and the averages reported.

Initial	Deflections in inches Forces in Grams					MIN			NOM		
	<u>0.0023</u>	<u>0.0046</u>	<u>0.0069</u>	<u>0.0092</u>	<u>0.0115</u>	<u>0.0138</u>	<u>0.0167</u>	<u>0.0184</u>	<u>0.0197</u>	<u>0.0230</u>	SET
Averages	8.21	17.30	26.63	35.11	43.11	50.21	58.33	62.56	65.55	72.27	0.0039
Min	2.80	12.30	21.40	30.40	38.50	46.00	54.50	58.90	62.30	69.60	0.0032
Max	9.80	19.20	28.50	37.40	45.30	52.60	60.70	65.00	68.00	74.70	0.0043
St. Dev	2.101	2.247	2.217	2.159	1.962	1.968	1.857	1.892	1.830	1.741	0.0003
Count	12	12	12	12	12	12	12	12	12	12	12

After Thermals	Deflections in inches Forces in Grams						MIN		NOM	MAX	
	<u>0.0023</u>	<u>0.0046</u>	<u>0.0069</u>	<u>0.0092</u>	<u>0.0115</u>	<u>0.0138</u>	<u>0.0167</u>	<u>0.0184</u>	<u>0.0197</u>	<u>0.0230</u>	SET
Averages	0.01	0.02	0.09	5.85	13.23	21.16	31.29	37.44	42.13	54.07	0.0073
Min	-0.10	-0.10	-0.10	4.00	11.60	19.10	29.00	34.70	39.50	50.90	0.0067
Max	0.10	0.20	0.60	7.60	14.90	23.10	33.20	39.70	44.60	56.90	0.0081
St. Dev	0.090	0.103	0.211	1.123	1.165	1.391	1.493	1.524	1.546	1.629	0.0004
Count	12	12	12	12	12	12	12	12	12	12	12

INSULATION RESISTANCE (IR):

	Pin to Pin				
	Mated	Unmated			
Minimum	HSEC8/Edge Card	HSEC8			
Initial	100000	100000			
Thermal	100000	100000			
Humidity	100000	100000			

	Row to Row					
	Mated	Unmated				
Minimum	HSEC8/Edge Card	HSEC8				
Initial	100000	100000				
Thermal	100000	100000				
Humidity	100000	100000				

Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A
Part description: High Sp	eed Edge Card Assembly

DIELECTRIC WITHSTANDING VOLTAGE (DWV):

Voltage Rating Summary					
Minimum HSEC8/Edge Card					
Break Down Voltage	960				
Test Voltage	720				
Working Voltage	240				

Pin to Pin				
Initial Test Voltage	Passed			
After Thermal Test Voltage	Passed			
After Humidity Test Voltage	Passed			

Row to Row				
Initial Test Voltage	Passed			
After Thermal Test Voltage	Passed			
After Humidity Test Voltage	Passed			

 Tracking Code: 218303_Report_Rev 2
 Part #: HSEC8-150-01-S-DV-A

 Part description: High Speed Edge Card Assembly

DATA SUMMARIES Continued

LLCR:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, LLCR 221.exe, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Gas Tight HSEC8-150-S-DV-A/ 0.056" Edge Card

	LLCR Measurement	Summaries by Pin Type		
Date	10/11/2012	10/12/2012		
Room Temp (Deg C)	22	22		
Rel Humidity (%)	32	32		
Technician	Aaron McKim	Aaron McKim		
mOhm values	Actual	Delta		
	Initial	Acid Vapor		
	Pin Type 1: Signal			
	Pin Ty	pe 1: Signal		
Average		be 1: Signal 0.10		
Average St. Dev.				
0	6.18	0.10		
St. Dev.	6.18 0.36	0.10 0.09		
St. Dev. Min	6.18 0.36 5.36	0.10 0.09 0.00		

LLCR Delta Count by Category								
	Stable	Minor	Acceptable	Marginal	Unstable	Open		
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000		
Acid Vapor	192	0	0	0	0	0		
Part description: High Speed Edge Card Assembly

DATA SUMMARIES Continued

LLCR:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Thermal Age

HSEC8-150-01-S-DV-A/ 0.056" Edge Card

Ū.	LLCR Measureme	nt Summaries by Pin Type
Date	10/17/2012	10/29/2012
Room Temp (Deg C)	22	22
Rel Humidity (%)	35	28
Technician	Aaron McKim	Aaron McKim
mOhm values	Actual	Delta
	Initial	Thermal
	Pin T	ype 1: Signal
Average	5.89	2.71
St. Dev.	0.33	1.87
Min	5.29	0.35
Max	7.74	11.54
Summary Count	192	192
Total Count	192	192

		LLCR D	elta Count by	Category		
	Stable	Minor	Acceptable	Marginal	Unstable	Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
Thermal	170	21	1	0	0	0

Part description: High Speed Edge Card Assembly

DATA SUMMARIES Continued

LLCR:

1) A total of 192 points were measured.

- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ------ Unstable
 - f. >+2000 mOhms:----- Open Failure

Thermal Age

HSEC8-150-01-S-DV-A/0.068" Edge Card

-	LLCR Measurement Summaries by Pin Type		
Date	10/17/2012	10/29/2012	
Room Temp (Deg C)	22	22	
Rel Humidity (%)	35	28	
Technician	Aaron McKim	Aaron McKim	
mOhm values	Actual	Delta	
	Initial	Thermal	
	Pin Type	1: Signal	
Average	5.27	1.16	
St. Dev.	0.25	0.70	
Min	4.84	0.01	
Max	6.24	4.72	
Summary Count	192	192	
Total Count	192	192	

		LLCR D	elta Count by	Category		
	Stable	Minor	Acceptable	Marginal	Unstable	Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
Thermal	192	0	0	0	0	0

art description: High Speed Edge Card Assembly

DATA SUMMARIES Continued

LLCR:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Mating/ Unmating Durability HSEC8-150-01-S-D-V-A/0.056" Edge Card

1-5-D-V-A/0.050° Euge Caru					
	LLCR	Measurement	Summaries by	Pin Type	
Date	10/18/2012	10/24/2012	10/29/2012	11/9/2012	
Room Temp (Deg C)	22	22	22	22	
Rel Humidity (%)	35	35	28	31	
Technician	Aaron McKim	Aaron McKim	Aaron McKim	Aaron McKim	
mOhm values	Actual	Delta	Delta	Delta	
	Initial	100 Cycles	Therm Shck	Humidity	
		Pin Type	e 1: Signal		
Average	5.86	0.38	0.41	0.93	
St. Dev.	0.36	0.30	0.34	1.03	
Min	4.98	0.00	0.00	0.01	
Max	7.83	1.33	1.94	7.41	
Summary Count	192	192	192	192	
Total Count	192	192	192	192	

LLCR Delta Count by Category						
	Stable	Minor	Acceptable	Marginal	Unstable	Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
100 Cycles	192	0	0	0	0	0
Therm Shck	192	0	0	0	0	0
Humidity	191	1	0	0	0	0

DATA SUMMARIES Continued

LLCR:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

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Mating/Unmating Durability HSEC8-150-01-S-DV-A/ 0.068" Edge Ca

50-01-S-DV-A/ 0.068" I)-01-S-DV-A/ 0.068" Edge Card					
	LLCR I	Measurement S	Summaries by l	Pin Type		
Date	10/18/2012	10/24/2012	10/29/2012	11/9/2012		
Room Temp (Deg C)	22	22	22	22		
Rel Humidity (%)	35	35	29	30		
Technician	Aaron McKim	Aaron McKim	Aaron McKim	Aaron McKim		
mOhm values	Actual	Delta	Delta	Delta		
	Initial	100 Cycles	Therm Shck	Humidity		
		Pin Type	e 1: Signal			
Average	5.14	0.27	0.27	0.65		
St. Dev.	0.22	0.56	0.28	0.85		
Min	4.65	0.01	0.00	0.00		
Max	5.87	7.57	2.63	7.24		
Summary Count	192	192	192	192		
Total Count	192	192	192	192		

LLCR Delta Count by Category						
	Stable	Minor	Acceptable	Marginal	Unstable	Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
100 Cycles	191	1	0	0	0	0
Therm Shck	192	0	0	0	0	0
Humidity	191	1	0	0	0	0

DATA SUMMARIES Continued

LLCR:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, LLCR 221.exe, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Mechanical Shock & Random Vibration HSEC8-150-01-S-DV-A/ 0.056" Edge Card

	LLCR Measuremen	t Summaries by Pin Type
Date	10/18/2012	10/25/2012
Room Temp (Deg C)	22	22
Rel Humidity (%)	36	38
Technician	Aaron McKim	Aaron McKim
mOhm values	Actual	Delta
	Initial	Shock-Vib
	Pin Ty	pe 1: Signal
Average	5.92	0.31
St. Dev.	0.43	0.26
Min	5.13	0.01
Max	8.29	1.17
Summary Count	192	192
Total Count	192	192

		LLCR D	elta Count by	Category		
	Stable	Minor	Acceptable	Marginal	Unstable	Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
Shock-Vib	192	0	0	0	0	0

Nanosecond Event Detection

Shock and Vibration Event Detection Summary				
Contacts tested	60			
Test Condition	C, 100g's, 6ms, Half-Sine			
Shock Events	0			
Test Condition	V-B, 7.56 rms g			
Vibration Events	0			
Total Events	0			

DATA SUMMARIES Continued

LLCR:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Mechanical Shock & Random Vibration HSEC8-150-01-S-DV-A/ 0.068" Edge Card

	LLCR Measurement	Summaries by Pin Type
Date	10/18/2012	10/19/2012
Room Temp (Deg C)	22	22
Rel Humidity (%)	36	31
Technician	Aaron McKim	Aaron McKim
mOhm values	Actual	Delta
	Initial	Shock-Vib
	Pin Typ	e 1: Signal
Average	5.56	0.17
St. Dev.	0.27	0.20
St. Dev. Min	0.27 5.00	0.20 0.00
	-	
Min	5.00	0.00

	LLCR Delta Count by Category						
	Stable Minor Acceptable Marginal Unstable Open						
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000	
Shock-Vib	192	0	0	0	0	0	

Part description: High Speed Edge Card Assembly

DATA SUMMARIES Continued

LLCR 250 Cycles:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, LLCR 221.exe, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Extended Life 250 Cycles: HSEC8-150-01-S-DV-A/ 0.068" Edge Card

1-5-D - A/ 0.000 Euge Cal	-S-DV-A/ 0.000 Euge Caru					
	LLCR Measurement Summaries by Pin Type					
Date	10/15/2012	10/16/2012	10/22/2012	11/2/2012		
Room Temp (Deg C)	22	22	22	22		
Rel Humidity (%)	35	31	37	35		
Technician	Aaron McKim	Aaron McKim	Aaron McKim	Aaron McKim		
mOhm values	Actual	Delta	Delta	Delta		
	Initial	250 Cycles	Therm Shck	Humidity		
		Pin Type	e 1: Signal			
Average	5.31	0.36	0.37	0.50		
St. Dev.	0.28	0.28	0.38	0.82		
Min	4.64	0.00	0.00	0.00		
Max	6.08	2.61	3.80	7.08		
Summary Count	192	192	192	192		
	100	100	100	100		
Total Count	192	192	192	192		

LLCR Delta Count by Category						
	Stable	Stable Minor Acceptable Marginal Unstable Op				Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
250 Cycles	192	0	0	0	0	0
Therm Shck	192	0	0	0	0	0
Humidity	190	2	0	0	0	0

Part description: High Speed Edge Card Assembly

DATA SUMMARIES Continued

LLCR 500 Cycles:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. <= +5.0 mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Extended Life 500 Cycles:

HSEC8-150-01-S-DV-A/ 0.068" Edge Card

Ũ	LLCR Measurement Summaries by Pin Type				
Date	10/15/2012	10/18/2012	10/22/2012	11/2/2012	
Room Temp (Deg C)	22	22	22	22	
Rel Humidity (%)	33	43	37	35	
Technician	Aaron McKim	Aaron McKim	Aaron McKim	Aaron McKim	
mOhm values	Actual	Delta	Delta	Delta	
	Initial	500 Cycles	Therm Shck	Humidity	
		Pin Type	1: Signal		
Average	5.22	0.35	0.45	0.71	
St. Dev.	0.29	0.33	0.33	0.97	
Min	4.63	0	0	0	
Max	6.32	2.29	1.9	10.08	
Summary Count	192	192	192	192	
Total Count	192	192	192	192	

LLCR Delta Count by Category						
	Stable	Stable Minor Acceptable Marginal Unstable Open				Open
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000
500 Cycles	192	0	0	0	0	0
Therm Shck	192	0	0	0	0	0
Humidity	191	0	1	0	0	0

Part description: High Speed Edge Card Assembly

DATA SUMMARIES Continued

LLCR 1000 Cycles:

- 1) A total of 192 points were measured.
- 2) EIA-364-23, Low Level Contact Resistance Test Procedure for Electrical Connectors and Sockets.
- 3) A computer program, *LLCR 221.exe*, ensures repeatability for data acquisition.
- 4) The following guidelines are used to categorize the changes in LLCR as a result from stressing.
 - a. $\leq +5.0$ mOhms: ----- Stable
 - b. +5.1 to +10.0 mOhms:----- Minor
 - c. +10.1 to +15.0 mOhms: ----- Acceptable
 - d. +15.1 to +50.0 mOhms: ----- Marginal
 - e. +50.1 to +2000 mOhms ----- Unstable
 - f. >+2000 mOhms:----- Open Failure

Extended Life 1000 Cycles: HSEC8-150-01-S-DV-A/ 0.068" Edge Card

B-DV-A 0.000 Euge Ca	-DV-A/0.000 Euge Caru					
	LLCR Measurement Summaries by Pin Type					
Date	10/15/2012	10/22/2012	10/29/2012	11/9/2012		
Room Temp (Deg C)	22	21	22	22		
Rel Humidity (%)	32	38	28	32		
Technician	Aaron McKim	Aaron McKim	Aaron McKim	Aaron McKim		
mOhm values	Actual	Delta	Delta	Delta		
	Initial	1000 Cycles	Therm Shck	Humidity		
		Pin Type	e 1: Signal			
Average	5.28	0.68	0.69	0.81		
St. Dev.	0.24	0.67	0.71	1.01		
Min	4.71	0.00	0.00	0.00		
Max	5.91	4.41	4.53	6.05		
Summary Count	192	192	192	192		
Total Count	192	192	192	192		
-						

LLCR Delta Count by Category							
	Stable	Stable Minor Acceptable Marginal Unstable Open				Open	
mOhms	<=5	>5 & <=10	>10 & <=15	>15 & <=50	>50 & <=1000	>1000	
1000 Cycles	192	0	0	0	0	0	
Therm Shck	192	0	0	0	0	0	
Humidity	189	3	0	0	0	0	

Tracking Code: 218303 Report Rev 2

Part #: HSEC8-150-01-S-DV-A Part description: High Speed Edge Card Assembly

EQUIPMENT AND CALIBRATION SCHEDULES

Equipment #: MO-04 Description: Multimeter /Data Acquisition System Manufacturer: Keithley Model: 2700 Serial #: 0798688 Accuracy: See Manual ... Last Cal: 03/27/2012, Next Cal: 03/27/2013

Equipment #: MO-11 Description: System Switch Multimeter /Data Acquisition System Manufacturer: Keithley Model: 3706 Serial #: Accuracy: See Manual ... Last Cal: 09/24/2012, Next Cal: 09/30/2013

Equipment #: THC-01 **Description:** Temperature/Humidity Chamber Manufacturer: Thermotron Model: SE-1000-6-6 Serial #: 31808 Accuracy: See Manual ... Last Cal: 09/18/2012, Next Cal: 09/18/2013

Equipment #: TSC-01 **Description:** Vertical Thermal Shock Chamber Manufacturer: Cincinnatti Sub Zero Model: VTS-3-6-6-SC/AC Serial #: 10-VT14993 Accuracy: See Manual ... Last Cal: 05/13/2012, Next Cal: 05/13/2013

Equipment #: OV-5 Description: Forced Air Oven, 5 Cu. Ft., 120 V Manufacturer: Sheldon Mfg. Model: CE5F Serial #: 02008008 Accuracy: +/- 5 deg. C ... Last Cal: 05/29/2012, Next Cal: 05/29/2013

Equipment #: TCT-04 Description: Dillon Quantrol TC2 Test Stand Manufacturer: Dillon Quantrol Model: TC2 Serial #: 04-1041-04 Accuracy: Speed Accuracy: +/- 5% of indicated speed; Displacement: +/- 5 micrometers. ... Last Cal: 05/03/2012, Next Cal: 05/03/2013

Equipment #: TCT-06 Description: Test Resources Test Stand Manufacturer: Test Resources Model: 100R250-12 Serial #: 0710191-C Accuracy: See manual

Equipment #: TCT-07 Description: Chatillon Manufacturer: Chatillon Model: LF Plus Serial #: LF1310 Accuracy: See Manual ... Last Cal: 07/13/2012, Next Cal: 07/13/2013

Equipment #: TCT-05 Description: Chatillon TCD Series Manufacturer: Chatillon Model: TCD2255 Serial #: TCD0071 Accuracy: See Manual ... Last Cal: 11/01/2012, Next Cal: 11/01/2013

Equipment #: LVDT-01 Description: Linear variable differential transducer Manufacturer: Trans-Tek Model: 240/0-0.250 Serial #: LVDT-01 Accuracy: ±0.5% OF F.S. ... Last Cal: 11/01/2012, Next Cal: 05/01/2013

Equipment #: HPM-01 Description: Hipot Megommeter Manufacturer: Hipotronics Model: H306B-A Serial #: M9905004 Accuracy: 2 % Full Scale Accuracy ... Last Cal: 11/30/2011, Next Cal: 11/30/2012

Equipment #: PS-11 Description: Power Supply Manufacturer: Agilent Tech Model: N57491 Serial #: US11M7700J Accuracy: See Manual

Tracking Code: 218303_Report_Rev 2	Part #: HSEC8-150-01-S-DV-A
Part description: High Sp	eed Edge Card Assembly

Equipment #: RS-09 Description: Shunt Manufacturer: EMPRO Model: HA10050 Serial #: HA10050 Accuracy: ±0.25%RDG ... Last Cal: 5/30/2012, Next Cal: 5/30/2013

Equipment #: TCS-005-046 Description: Calibrated Thermocouples Manufacturer: Samtec, Inc. Model: Serial #: Accuracy: ... Last Cal: 5/30/2012, Next Cal: 05/30/2013

Equipment #: SVC-01 Description: Shock and Vibration Table Manufacturer: Data Physics Model: LE-DSA-10-20K Serial #: 10037 Accuracy: See Manual ... Last Cal: 01/12/2012, Next Cal: 01/12/2013